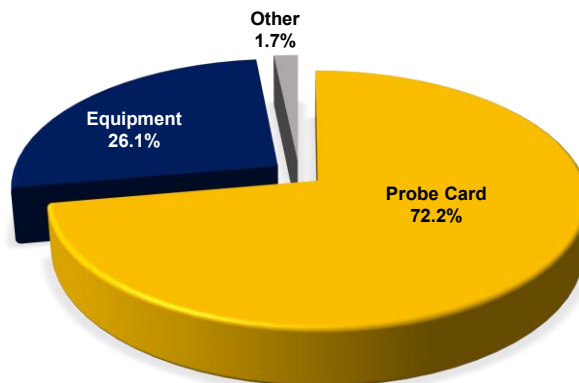


# 旺矽科技股份有限公司 2025 Annual Result Meeting 櫃買中心法說會

2026.03.30

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## 2025依產品別營收分布



## 合併營收2025 vs. 2024

NT\$ 000

	2025	2024	YoY
Q1	2,828,698	2,046,692	38.2%
Q2	3,292,785	2,392,994	37.6%
Q3	3,413,781	2,729,350	25.1%
Q4	3,835,917	3,002,825	27.7%
Q1-Q4	13,371,181	10,171,861	31.5%

## 損益表4Q25 vs. 3Q25

NT\$ 000

	4Q25	3Q25	QoQ
Net Revenue	3,835,917	3,413,781	12.4%
Gross profit	2,062,769	1,822,436	13.2%
Income from Operations	959,261	895,873	7.1%
Non-op. Income	188,237	156,941	19.9%
Pre-tax Income	1,147,498	1,052,814	9.0%
Net Income	947,760	876,674	8.1%
EPS	9.81	9.30	5.5%

## 損益表4Q25 vs. 4Q24

NT\$ 000

	4Q25	4Q24	YoY
Net Revenue	3,835,917	3,002,825	27.7%
Gross profit	2,062,769	1,687,760	22.2%
Income from Operations	959,261	753,200	27.4%
Non-op. Income	188,237	103,129	82.5%
Pre-tax Income	1,147,498	856,329	34.0%
Net Income	947,760	715,007	32.6%
EPS	9.81	7.59	29.2%

## 損益表2025 vs. 2024

NT\$ 000

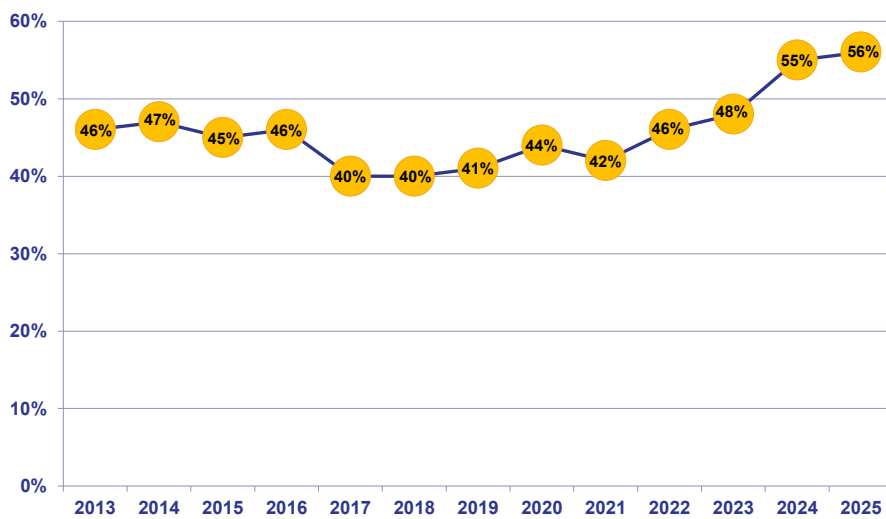
	2025	2024	YoY
Net Revenue	13,371,181	10,171,861	31.5%
Gross profit	7,427,809	5,560,970	33.6%
Income from Operations	3,774,540	2,482,672	52.0%
Non-op. Income	69,728	312,044	-77.6%
Pre-tax Income	3,844,268	2,794,716	37.6%
Net Income	3,175,392	2,299,887	38.1%
EPS	33.49	24.42	37.1%

## 資產負債表2025

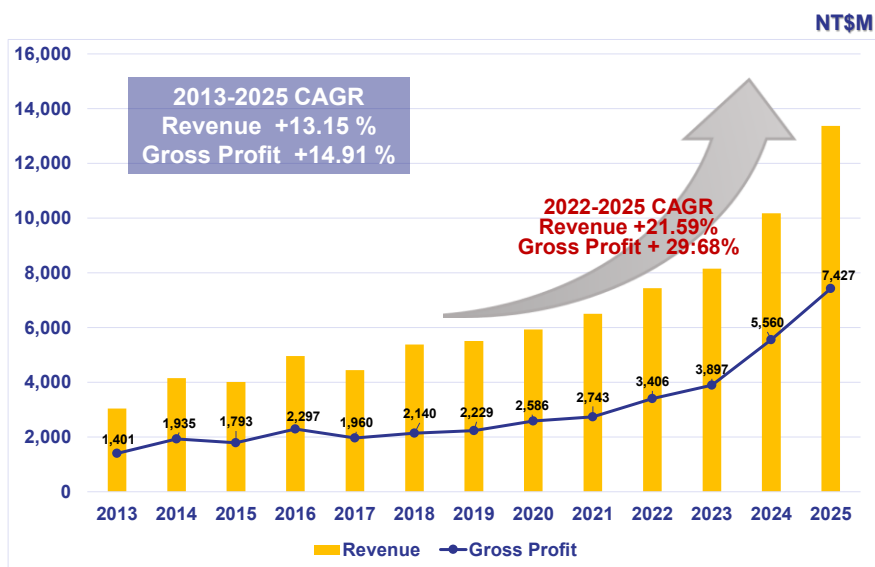
	NT\$M			
	2025		2024	
Cash and Cash Equivalents	5,437	23%	3,695	23%
Fixed Assets	10,685	44%	6,973	42%
Total Assets	24,002	100%	16,478	100%
LT Debt	1,337	5%	1,304	8%
Shareholders' Equity	14,578	61%	9,306	56%
EBITDA	3,844	29%	2,794	28%

\*EBITDA=operating income + depreciation & amortization expenses

## 歷年毛利率



## 歷年營收與毛利



## 2025 年全球半導體市場由高效能運算 ( HPC ) 驅動

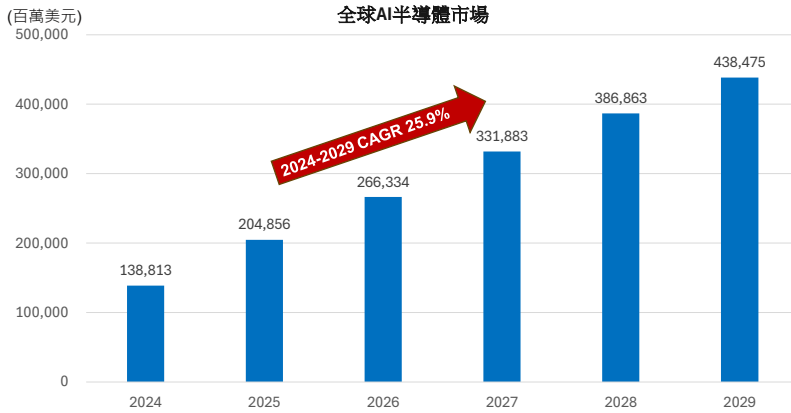
- Global semi market extended its high growth from 2024, reaching total market size of US\$864.3bn in 2026 at nearly 12% growth rate, mainly driven by HPC incl. AI related demand.
- HPC chips remains the main driver for semi industry in next few years, exceeding US\$500bn in 2029.



Source: 工研院產科國際所

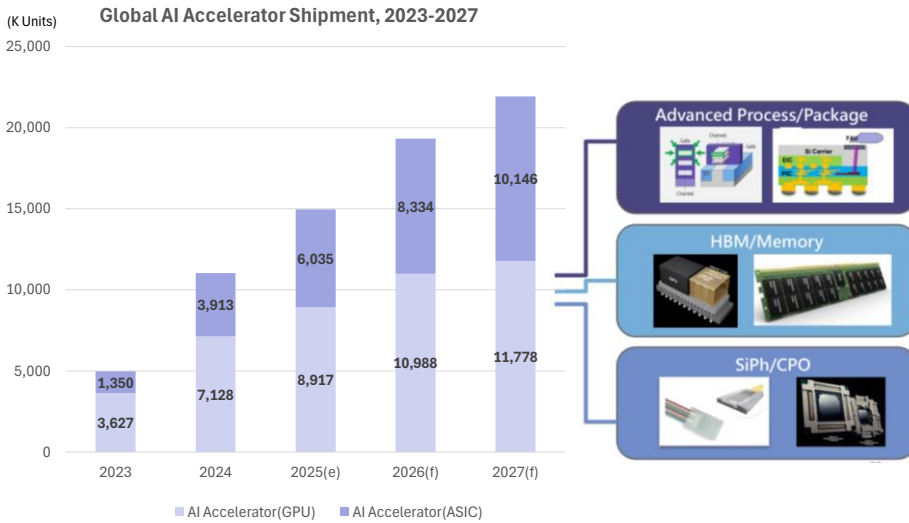
## AI 成為半導體產業的關鍵成長動能

- AI related rev to reach US\$438.2bn in 2029 with CAGR 25.9% from FY24-29.
- After an explosive booming demand from 2024, AI started to enter a stable L/T growth phase afterward.



註：數據源自於Gartner於2025年10月所發布之數據  
資料來源：工研院產科國際所

## AI 加速器成為核心議題



Source: DIGITIMES

# MPIProbe Card

Advanced Wafer Sort Test Solutions

## Vertical / MEMS Cantilever



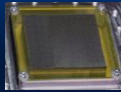
### Features



Fine Pitch



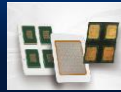
MEMS



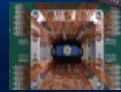
High Pin Count



High Speed



Substrate



Hand-wired



RF

MPI CORPORATION

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# MPIThermal

Hot and Cold Air Flow  
Environmental Temperature Test

-100°C  +300°C  
**ThermalAir Series**  
Temperature Testing Systems



### Applications & Industry Segments



Semiconductor



Automotive



Aerospace



Telecommunications



Fiber Optic



Electronics



Sensors



Advanced Technology

MPI CORPORATION

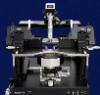
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# MPI Advanced Semiconductor Test

Engineering Probe Systems  
and  
RF Probe Products



50 – 300 mm



26 – 110 GHz

Applications & Industry Segments



Device Characterization



High Power



RF & mmW



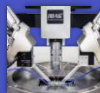
Design Validation



Failure Analysis



Wafer Level Reliability



Silicon Photonics



Laser Cutter

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# Thank You



<http://www.mpi-corporation.com>

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